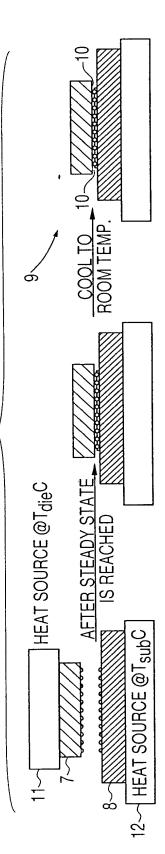
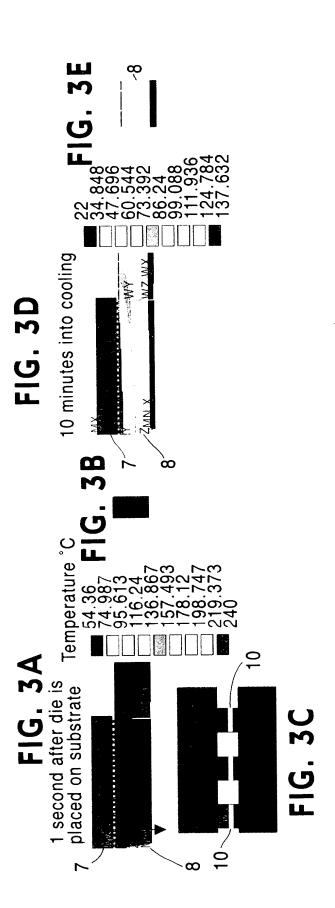
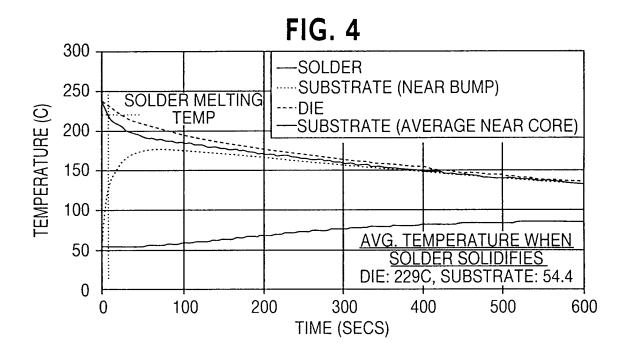


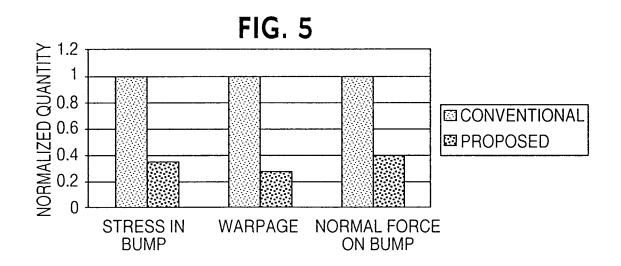
FIG. 2

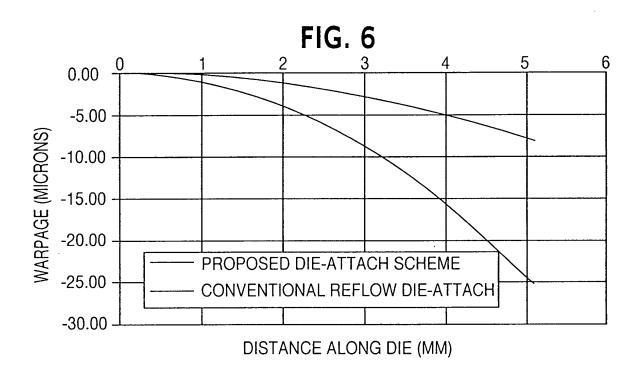


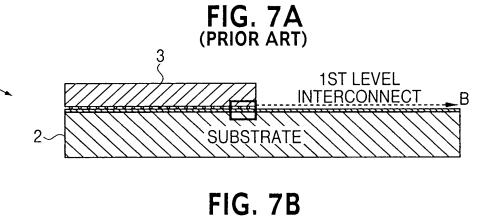
ALIGN, AND PLACE DIE ON SUBSTRATE COOL TO ROOM-TEMPERATURE











(PRIOR ART)

DIE

HIGH MELTING TEMP MATERIAL

6

LOW MELTING TEMP
MATERIAL MELTS DURING
CHIP-ATTACH